

## C0603X332K5RECTU

Aliases (C0603X332K5REC7867)

Specifications

Insulation Resistance

ESD SMD Comm X7R, Ceramic, 3,300 pF, 10%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0603, 0.4 mm



General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	7.3 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
ESD Level per AEC-Q200	12,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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